

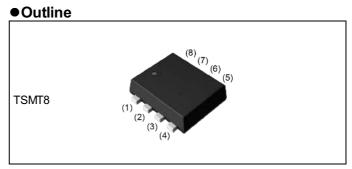
**QH8K26** 

40V Nch + Nch Small Signal MOSFET

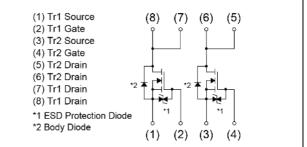
V <sub>DSS</sub>	40V
R <sub>DS(on)</sub> (Max.)	38mΩ
I <sub>D</sub>	±7.0A
P <sub>D</sub>	2.6W

## Features

- 1) Low on resistance
- 2) Small Surface Mount Package (TSMT8)
- 3) Pb-free lead plating ; RoHS compliant
- 4) Halogen Free



## ●Inner circuit



### Packaging specifications

	Packing	Embossed Tape
	Reel size (mm)	180
Туре	Tape width (mm)	8
	Quantity (pcs)	3000
	Taping code	TR
	Marking	K26

### • Absolute maximum ratings ( $T_a = 25^{\circ}C$ ,unless otherwise specified) <Tr1 and Tr2>

Parameter	Symbol	Value	Unit
Drain - Source voltage	V <sub>DSS</sub>	40	V
Continuous drain current	۱ <sub>D</sub> *1	±7.0	А
Pulsed drain current	۱ <sub>DP</sub> *2	±18	А
Gate - Source voltage	V <sub>GSS</sub>	±12	V
Avalanche current, single pulse	I <sub>AS</sub> *3	12	А
Avalanche energy, single pulse	E <sub>AS</sub> *3	1.0	mJ
	P <sub>D</sub> <sup>*1</sup>	2.6	
Power dissipation (total)	P <sub>D</sub> <sup>*4</sup>	1.5	W
	P <sub>D</sub> *5	1.1	
Junction temperature	Tj	150	C°
Operating junction and storage temperature range	T <sub>stg</sub>	-55 to +150	°C

Application
Switching
Motor Drive

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#### •Thermal resistance

Deremeter	Symbol	Values			Linit
Parameter	Symbol	Min.	Тур.	Max.	Unit
Thermal registeres, junction, embient (total)	$R_{thJA}^{*4}$	-	-	83.3	°C/W
Thermal resistance, junction - ambient (total)	$R_{thJA}^{*5}$	-	-	113	

## •Electrical characteristics (T<sub>a</sub> = 25°C) <Tr1 and Tr2>

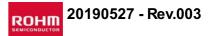
Deremeter	Cumph of	Conditions	V		Values		
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit	
Drain - Source breakdown voltage	V <sub>(BR)DSS</sub>	$V_{(BR)DSS}$ $V_{GS} = 0V, I_D = 1mA$		-	-	V	
Breakdown voltage temperature coefficient	$\frac{\Delta V_{(BR)DSS}}{\Delta T_{i}}  _{D} = 1 \text{mA}$		-	27.3	-	mV/°C	
Zero gate voltage drain current	I <sub>DSS</sub>	$I_{DSS}$ $V_{DS} = 40V, V_{GS} = 0V$		-	1	μΑ	
Gate - Source leakage current	I <sub>GSS</sub>	$I_{GSS}$ $V_{GS} = \pm 12V, V_{DS} = 0V$		-	±10	μA	
Gate threshold voltage	V <sub>GS(th)</sub>	$V_{GS(th)}$ $V_{DS}$ = 10V, $I_D$ = 1mA		-	2.5	V	
Gate threshold voltage temperature coefficient $\Delta V_{GS(th)}$ $\Delta T_j$ $I_D = 1mA$ referenced to 25°C		-	-	-4.6	-	mV/°C	
Static drain - source	D *6	V <sub>GS</sub> = 10V, I <sub>D</sub> = 7.0A	-	27	38		
on - state resistance	R <sub>DS(on)</sub> *6	V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 5.0A	-	35	50	mΩ	
Gate resistance	R <sub>G</sub>	f = 1MHz, open drain	-	7.1	-	Ω	
Forward Transfer Admittance	Y <sub>fs</sub>  * <sup>6</sup>	$V_{DS} = 5V, I_D = 5A$		-	-	S	

\*1 Pw  $\leq$  1s, Limited only by maximum temperature allowed.

\*2 Pw  $\leq 10\mu s$ , Duty cycle  $\leq 1\%$ 

\*3 L  $\simeq$  0.01mH, V\_{DD} = 20V, R\_G = 25 $\Omega$ , Starting T\_j = 25°C Fig.3-1,3-2

- \*4 Mounted on a ceramic board (30×30×0.8mm)
- \*5 Mounted on a FR4 (25×25×0.8mm)
- \*6 Pulsed



## •Electrical characteristics (T<sub>a</sub> = 25°C) <Tr1 and Tr2>

Parameter	Cumhal	Conditions	Values			Unit	
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit	
Input capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0V	-	275	-		
Output capacitance	C <sub>oss</sub>	V <sub>DS</sub> = 20V	-	80	-	pF	
Reverse transfer capacitance	C <sub>rss</sub>	f = 1MHz	-	23	-		
Turn - on delay time	t <sub>d(on)</sub> *6	$V_{DD} \simeq 20V, V_{GS}$ = 10V	-	8	-		
Rise time	t <sub>r</sub> *6	I <sub>D</sub> = 3.5A	-	18	-	20	
Turn - off delay time	$t_{d(off)}$ *6	R <sub>L</sub> = 5.7Ω	-	20	-	ns	
Fall time	t <sub>f</sub> *6	R <sub>G</sub> = 10Ω	-	3	-		

## •Gate charge characteristics ( $T_a = 25^{\circ}C$ ) <Tr1 and Tr2>

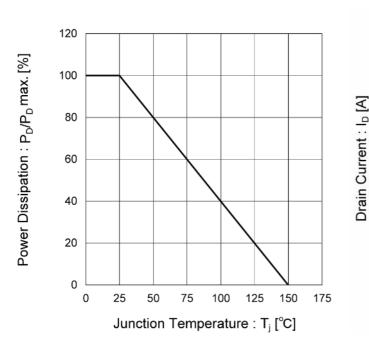
Deremeter	Cumphal	Conditions	Values			Linit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Total gate charge	Qg <sup>*6</sup>		-	2.9	-	
Gate - Source charge	Q <sub>gs</sub> *6	V <sub>DD</sub> ≃ 20V, I <sub>D</sub> = 7.0A V <sub>GS</sub> = 5.0V	-	1.4	-	nC
Gate - Drain charge	Q <sub>gd</sub> *6		-	0.6	-	

# •Body diode electrical characteristics (Source-Drain) ( $T_a = 25^{\circ}C$ )

<Tr1 and Tr2>

Parameter	Symbol	Conditions	Values			Unit
	Symbol Conditions		Min.	Тур.	Max.	Unit
Continuous forward current	۱ <sub>s</sub>	T - 25°0	-	-	1.25	^
Pulse forward current	I <sub>SP</sub> *2	T <sub>a</sub> = 25°C	-	-	18	A
Forward voltage	V <sub>SD</sub> *6	V <sub>GS</sub> = 0V, I <sub>S</sub> = 1.25A	-	-	1.2	V





## Fig.1 Power Dissipation Derating Curve

Fig.2 Maximum Safe Operating Area

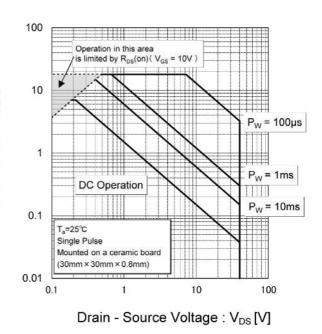
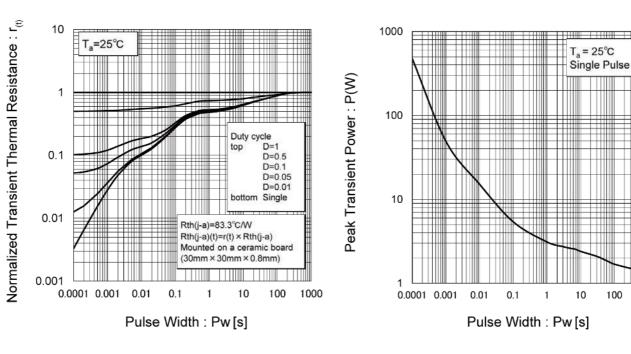


Fig.3 Normalized Transient Thermal Resistance vs. Pulse Width

Fig.4 Single Pulse Maximum Power dissipation

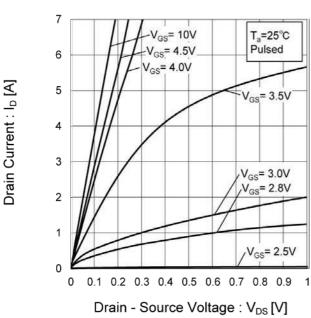


4/11



100

1000



### Fig.5 Typical Output Characteristics(I)

T<sub>a</sub>=25°C

Pulsed

V<sub>GS</sub>= 3.5V

V<sub>GS</sub>= 3.0V V<sub>GS</sub>= 2.8V

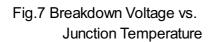
V<sub>GS</sub>= 2.5V

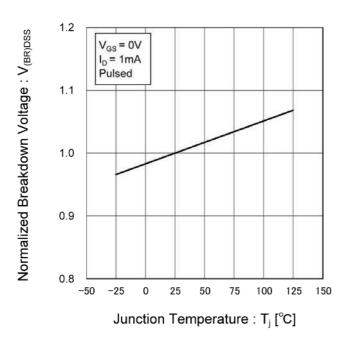
V<sub>GS</sub>= 10V V<sub>GS</sub>= 4.5V 6 -V<sub>GS</sub>= 3.0V V<sub>GS</sub>= 4.0V -V<sub>GS</sub>= 3.5V T<sub>a</sub>=25°C 5 Pulsed 4 3 V<sub>GS</sub>= 2.8V 2 1 V<sub>GS</sub>= 2.5V 0 0 2 3 4 5 6 7 10 1 8 9 Drain - Source Voltage : V<sub>DS</sub> [V]

## Fig.6 Typical Output Characteristics(II)

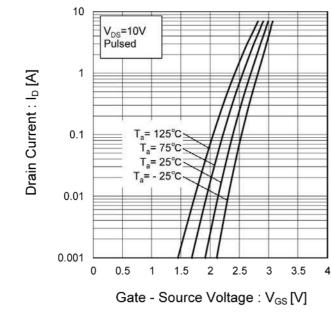
7

Drain Current : I<sub>D</sub> [A]



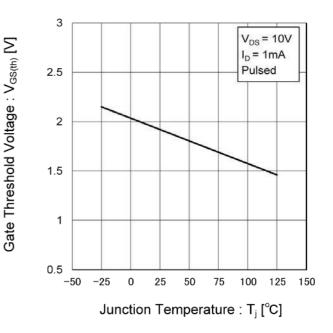




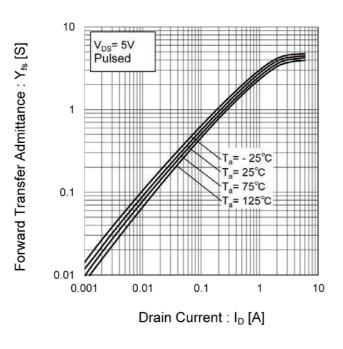


## Fig.8 Typical Transfer Characteristics

Fig.9 Gate Threshold Voltage vs. Junction Temperature



## Fig.10 Forward Transfer Admittance vs. Drain Current





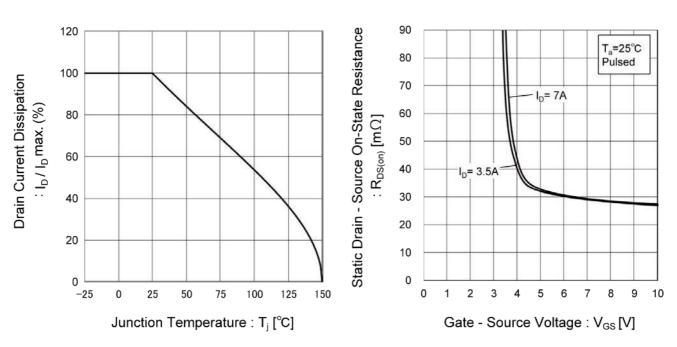
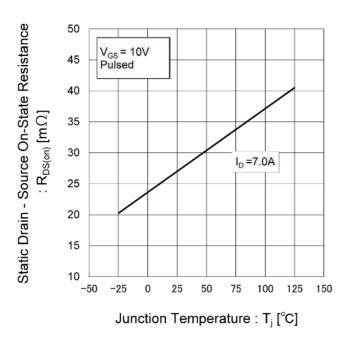


Fig.11 Drain Current Derating Curve

## Fig.12 Static Drain - Source On - State Resistance vs. Gate Source Voltage

Fig.13 Static Drain - Source On - State Resistance vs. Junction Temperature





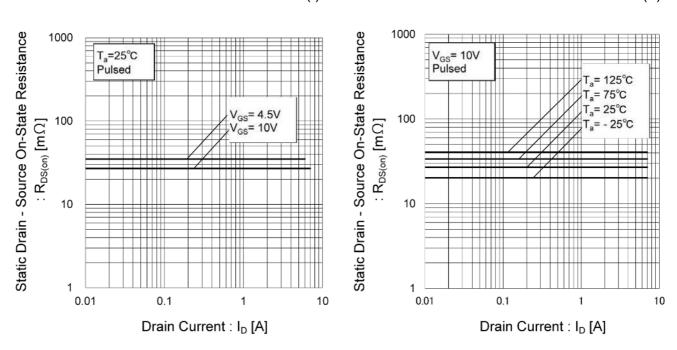
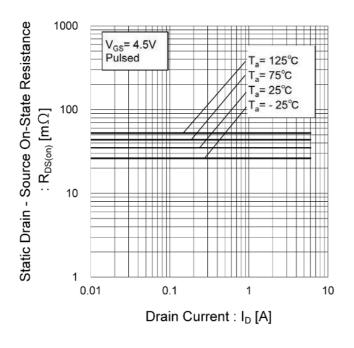


Fig.14 Static Drain - Source On - State Resistance vs. Drain Current (I) Fig.15 Static Drain - Source On - State Resistance vs. Drain Current (II)

Fig.16 Static Drain - Source On - State Resistance vs. Drain Current (III)







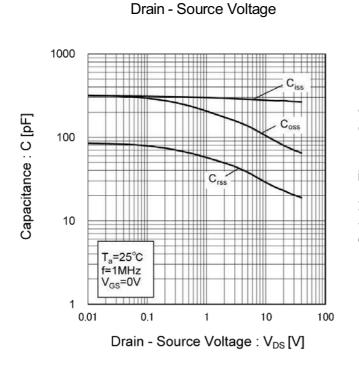


Fig.17 Typical Capacitance vs.

#### Fig.18 Switching Characteristics

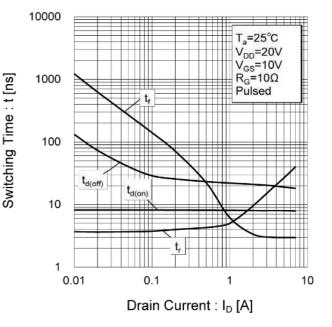


Fig.19 Dynamic Input Characteristics

Gate - Source Voltage : V<sub>GS</sub> [V]

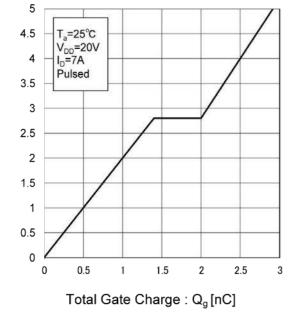
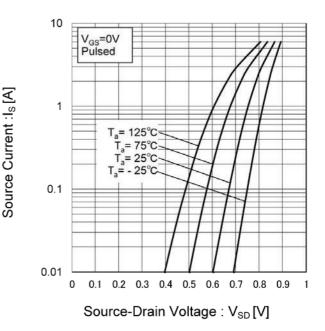


Fig.20 Source Current vs. Source Drain Voltage





## •Measurement circuits <It is the same for the Tr1 and Tr2>



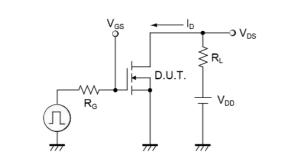


Fig.2-1 Gate Charge Measurement Circuit

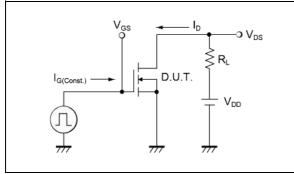


Fig.3-1 Avalanche Measurement Circuit

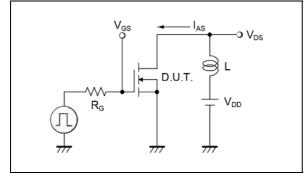
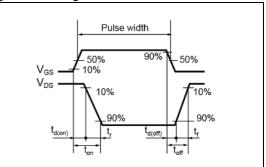
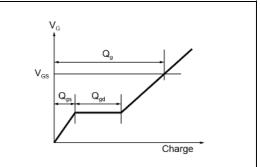


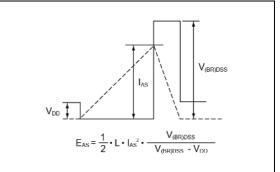
Fig.1-2 Switching Waveforms





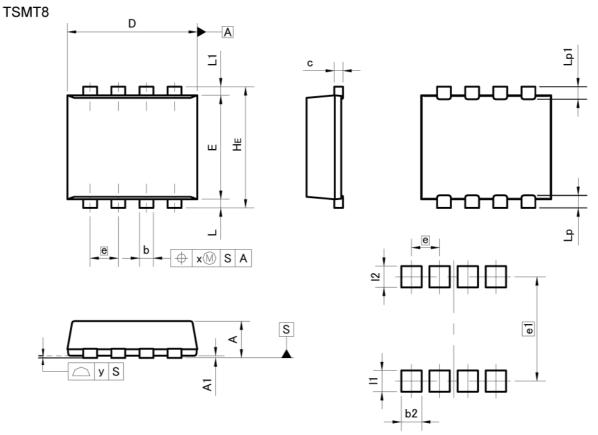


#### Fig.3-2 Avalanche Waveform





#### Dimensions



Pattern of terminal position areas [Not a pattern of soldering pads]

DIM	MILIM	ETERS	INC	HES
	MIN	MAX	MIN	MAX
A	0.75	0.85	0.030	0.033
A1	0.00	0.05	0.000	0.002
b	0.27	0.37	0.011	0.015
с	0.12	0.22	0.005	0.009
D	2.90	3.10	0.114	0.122
E	2.30	2.50	0.091	0.098
е	0.65		0.0	26
HE	2.70	2.90	0.106	0.114
L	0.10	0.30	0.004	0.012
L1	0.10	0.30	0.004	0.012
Lp	0.19	0.39	0.007	0.015
Lp1	0.19	0.39	0.007	0.015
x	275	0.10	1 <del>77</del> 3	0.004
v	800	0.10	1770	0.004

DIM	MILIMETERS		INC	HES
	MIN	MAX	MIN	MAX
b2	20 <del>14</del>	0.47	(H)	0.019
e1	2.	2.41		095
11	3 <del>71</del>	0.49	3 <del></del> )	0.019
12	8000	0.49		0.019

Dimension in mm/inches



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JAPAN	USA	EU	CHINA
CLASSⅢ	CLASSⅢ	CLASS II b	CLASSII
CLASSⅣ	CLASSII	CLASSⅢ	CLASSI

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  - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
  - [f] Sealing or coating our Products with resin or other coating materials
  - [g] Use of our Products without cleaning residue of flux (Exclude cases where no-clean type fluxes is used. However, recommend sufficiently about the residue.); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
  - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse, is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- 9. ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

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- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
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This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

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  - [a] the Products are exposed to sea winds or corrosive gases, including Cl<sub>2</sub>, H<sub>2</sub>S, NH<sub>3</sub>, SO<sub>2</sub>, and NO<sub>2</sub>
  - [b] the temperature or humidity exceeds those recommended by ROHM
  - [c] the Products are exposed to direct sunshine or condensation
  - [d] the Products are exposed to high Electrostatic
- 2. Even under ROHM recommended storage condition, solderability of products out of recommended storage time period may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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